

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of the Claims:

1-9. (Canceled).

10. (Currently Amended) A method for producing a micromechanical component using a sacrificial layer, comprising:

~~producing~~ creating a patterned porous region in a silicon substrate;
~~producing~~ creating a functional layer above the porous region; and
subsequently exposing the functional layer, the porous region being used at least partially as the sacrificial layer;
wherein the porous region is ~~producing~~ creating first and then the functional layer.

11. (Canceled).

12. (Currently Amended) The method as recited in Claim 10, wherein:

the [[step]] creating of ~~producing~~ the porous region includes ~~producing~~ creating a doped first region in the substrate in which no pores will form, and subsequently ~~producing~~ creating the porous region.

13. (Currently Amended) The method as recited in Claim 10, further comprising:

 patterning the functional layer; and
 ~~producing~~ creating additional layers above the porous region, the additional layers cooperating with the functional layer and being provided in patterned form.

14. (Previously Presented) The method as recited in Claim 10, further comprising:

 etching off in a dry-chemical manner the porous region below the functional layer.

15. (Currently Amended) A method for producing a micromechanical component using a sacrificial layer, comprising:

~~producing~~ creating a patterned porous region in a silicon substrate;
~~producing~~ creating a functional layer above the porous region; and
subsequently exposing the functional layer, the porous region being used at least partially as the sacrificial layer;

wherein the porous region includes a first porous partial region and a second porous partial region,

the second porous partial region has a higher porosity than the first porous partial region,

a cavity is formed in the second porous partial region by a thermal treatment, and
a cover layer remains in the first porous partial region.

16. (Previously Presented) The method as recited in Claim 15, further comprising:

in order to expose the functional layer, etching off at least the cover layer at least partially.

17. (Canceled).

18. (Canceled).

19. (New) The method as recited in Claim 10, further comprising:

etching off in a dry-chemical manner the porous region below the functional layer;
patterning the functional layer; and

creating additional layers above the porous region, the additional layers cooperating with the functional layer and being provided in patterned form;

wherein the creating of the porous region includes creating a doped first region in the substrate in which no pores will form, and subsequently creating the porous region..

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Reply to Office Action of December 12, 2008

Amendments to the Drawings:

The accompanying Replacement Sheets are for Figs. 1 to 4 and replace the original sheets. In Figs. 1 to 4, the lettering and numbering have been typewritten. No new matter has been added. Approval and entry are respectfully requested.

Attachments: 3 Replacement Sheets